IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reinternational and Pan-American copyright conventions.			nder both	This docume level parts, th	ent is a declaration	a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower claration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1					Form Type * Distribute	k	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
Supplier	Information														
Company name*				ompany unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-21			
Contact Na	ame	Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-E	Inv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	l Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-E	inv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number	Mfr Item	Mfr Item Number Mfr Iter		For Item Name EC D2PAK 15A 45V SHTKY		Effective Date	Vers	Version Manufacturing Site		V	Weight*	UOM	Unit Type	
		MBRB1545CTG REC D2P		REC D2PAK 15A			2024-05-21		VN5		1	420.1	mg	Each	
Ianufac	cturing Proccess Informa	ntion						•				,		,	
,	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 I		-STD-020 MSL	Rating	Peak Process Body Temperatur		ure Max Time at Peak Temperatu		ure Numb	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed			CU Alloy 1			260		C 30		30 secon		ds 3			
omments															
vel 1 - ma	aximum time at peak temperat	ure during sol	ldering is 10-3	30 seconds											
or more i	nformation regarding material	composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
irective 2015/863/EU amending RoHS irective 2011/65/EU amending RoHS Polystominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shave provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.34	mg	A	Lead (Pb)	7439-92-1	7a	10.773	mg
			Supplier	Tin (Sn)	7440-31-5		0.567	mg
Lead Frame	851.91	mg	В	Nickel (Ni)	7440-02-0		2.5557	mg
			Supplier	Copper (Cu)	7440-50-8		849.3542	mg
Mold Compound-Black	529.31			Epoxy resin	proprietary data		37.0517	mg
			Supplier	Phenolic Resin	Proprietary Data		15.8793	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		52.931	mg
			Supplier	Carbon Black (C)	1333-86-4		2.6465	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		420.8015	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Al	0.2	mg	Supplier	Aluminum (Al)	7429-90-5		0.2	mg